

# PATENT ASSIGNMENT

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<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Jong-soo RHYEE	03/17/2011
Sang-mock LEE	03/17/2011
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<b>State/Country:</b>	REPUBLIC OF KOREA
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	13077314
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<b>Total Attachments: 2</b> source=49W0845#page1.tif source=49W0845#page2.tif	

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**PATENT**  
**REEL: 026165 FRAME: 0015**

**ASSIGNMENT**

WHEREAS WE, **Jong-soo RHYEE** c/o Samsung Advanced Institute of Technology, San 14-1 Nongseo-dong, Giheung-gu, Yongin-si, Gyeonggi-do, Republic of Korea; and **Sang-mock LEE** c/o Samsung Advanced Institute of Technology, San 14-1 Nongseo-dong, Giheung-gu, Yongin-si, Gyeonggi-do, Republic of Korea (hereinafter collectively referred to as the “**ASSIGNORS**”), have invented certain new and useful improvements in:

**THERMOELECTRIC MATERIAL, AND THERMOELECTRIC MODULE AND  
THERMOELECTRIC DEVICE INCLUDING THE THERMOELECTRIC MATERIAL**

(hereinafter referred to as the “**INVENTION**”) which claims priority to Korean Application No. 10-2010-0029348, filed on 31 March 2010; and for which we are about to file an application for a United States Patent (hereinafter collectively referred to as the “**APPLICATIONS**”);

AND WHEREAS, **SAMSUNG ELECTRONICS CO., LTD.** (hereinafter referred to as “**ASSIGNEE**”), a corporation organized and existing under the laws of the Country of KOREA, having a place of business at **416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of Korea**, is desirous of acquiring an interest in any and all countries, in and to the **INVENTION**, the **APPLICATIONS**, and any and all Patents to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that for good and valuable consideration, the receipt of which is hereby acknowledged, we, the **ASSIGNORS**, have assigned and transferred, and hereby assign and transfer unto **ASSIGNEE**, the entire right, title and interest in and to the **INVENTION**, the **APPLICATIONS**, and any and all Patents that may be issued therefrom, in any and all countries, including any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to **ASSIGNEE**; and we do hereby agree that we will execute all papers necessary in connection with any and all patent applications when called upon to do so by **ASSIGNEE**, its successors or assigns, and that we will, at the cost and expense of **ASSIGNEE**, fully assist and cooperate in all matters in connection with any and all patent applications and Patents issuing thereon.

The undersigned declare that all statements made herein of his own knowledge are true and that all statements made on information and belief are believed to be true; and further that these

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statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the APPLICATIONS or any Patents issuing thereon.

Date: Mar 17 2011

Jong-soo Rhyee L.S.  
Jong-soo RHYEE

Date: Mar 17. 2011

Sang-mock Lee L.S.  
Sang-mock LEE